

What Is Claimed Is:

1. An adhesive composition, comprising:

an insulating resin;

a photopolymerization initiator; and

5 an oxetan compound.

2. The adhesive composition according to Claim 1,

comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive

composition.

10 3. The anisotropic conductive adhesive composition

according to Claim 1 or Claim 2, further comprising

electrically conductive particles.

15 4. A connected structure, wherein electrodes on a

plastic substrate and on a circuit board that are facing each

other are connected by the adhesive composition according to

any of Claims 1 to 3.